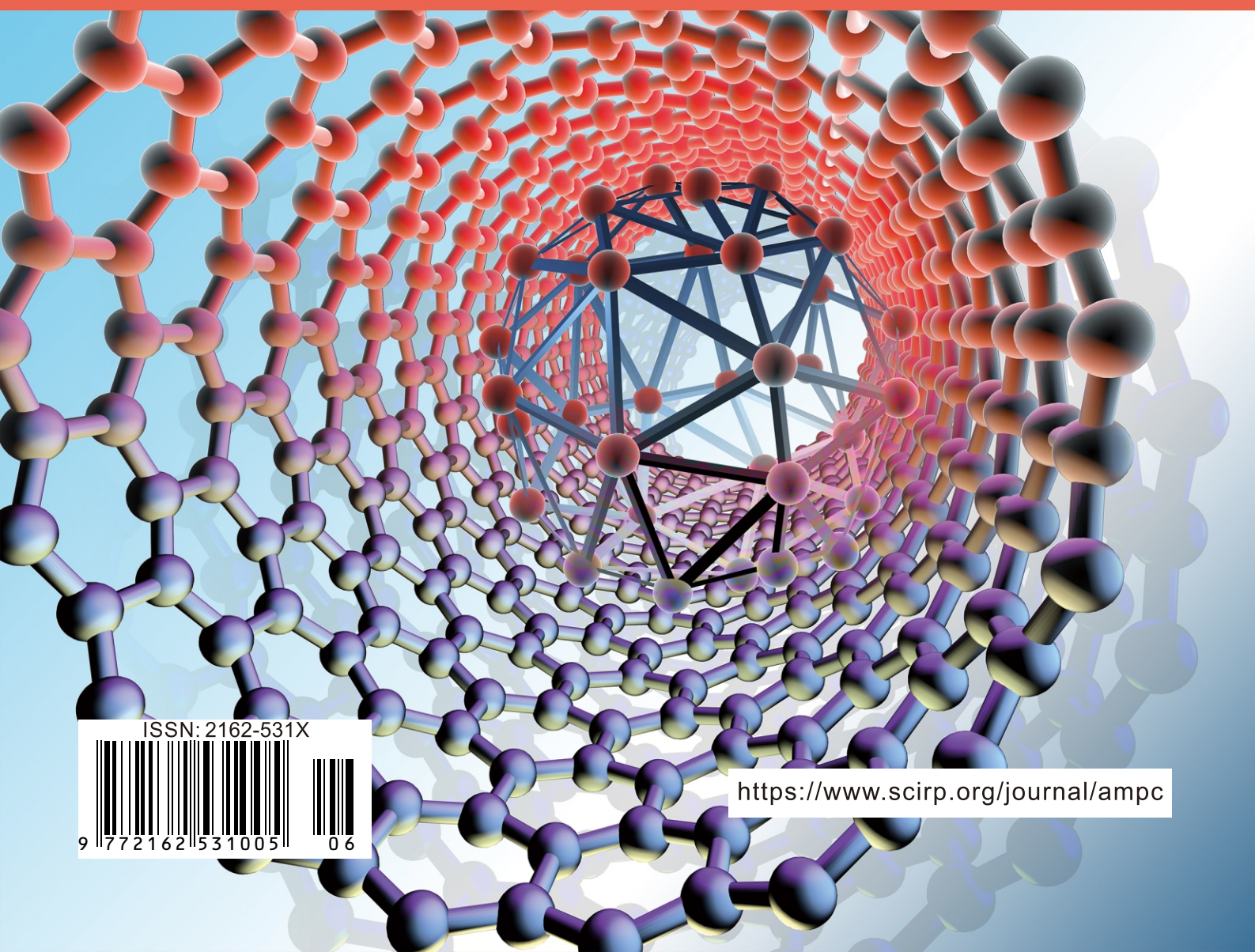


ISSN: 2162-531X

Volume 10, Number 6, June 2020



Advances in Materials Physics and Chemistry



ISSN: 2162-531X



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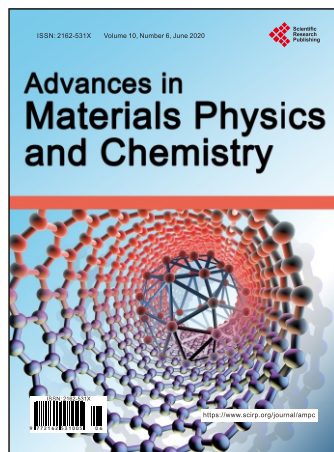
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